



BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.5600 mm
Board overall dimensions:	105.0000 mm x 105.0000 mm		
Min track/spacing:	0.1500 mm / 0.1500 mm	Min hole diameter:	0.3000 mm
Copper Finish:	ENIG	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

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